



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



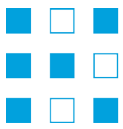
## Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China





## 275 No-Clean Cored Wire for Lead-Free and Leaded Alloys

### Product Description

Kester 275 Flux for cored solder wire was developed to provide superior wetting performance for hand soldering in the electronics industry. The chemistry is based on some of the same principles that have been safely used for years in mildly activated rosin fluxes. The use of 275 results in an extremely clear post-soldering residue without cleaning. The unique chemistry in 275 was also designed to reduce spattering common to most core fluxes. 275 can be used for both lead bearing and lead-free soldering.

#### Performance Characteristics:

- Colorless translucent residues
- Improves wetting performance
- Excellent solderability and fast wetting to a variety of surface finishes
- Eliminates the need and expense of cleaning
- Low smoke and odor
- Low spattering
- Compatible with leaded and lead-free alloys
- Classified as ROL0 per J-STD-004
- Compliant to Bellcore GR-78

### RoHS Compliance

This product meets the requirements of the Restriction of Hazardous Substances (RoHS) Directive, 2011/65/EU for the stated banned substances. (Applies only if this core flux is combined with a lead-free alloy)

### Reliability Properties

**Copper Mirror Corrosion:** Low  
Tested to J-STD-004, IPC-TM-650, Method 2.3.32

**Corrosion Test:** Low  
Tested to J-STD-004, IPC-TM-650, Method 2.6.15

**Silver Chromate:** Pass  
Tested to J-STD-004, IPC-TM-650, Method 2.3.33

**Chloride and Bromides:** None Detected  
Tested to J-STD-004, IPC-TM-650, Method 2.3.35

**Fluorides by Spot Test:** Pass  
Tested to J-STD-004, IPC-TM-650, Method 2.3.35.1

**Spread Test (typical):**  
Tested to J-STD-004, IPC-TM-650, Method 2.4.46

	Area of Spread mm <sup>2</sup> (in <sup>2</sup> )	
Flux Core Solder	Sn96.5Ag3.0Cu0.5	Sn63Pb37
285 Mildly Activated Rosin	213 (0.33)	335 (0.52)
245 No-Clean	200 (0.31)	348 (0.54)
275 No-Clean	219 (0.34)	361 (0.56)

**Surface Insulation Resistivity (SIR) 85C/85%RH, IPC (typical):** Pass  
Tested to J-STD-004, IPC-TM-650, Method 2.6.3.3

	Blank	275
Day 1	1.6*10 <sup>10</sup> Ω	1.1*10 <sup>10</sup> Ω
Day 4	1.2*10 <sup>10</sup> Ω	9.2*10 <sup>9</sup> Ω
Day 7	1.1*10 <sup>10</sup> Ω	8.6*10 <sup>9</sup> Ω

**Surface Insulation Resistivity (SIR) 40C/90%RH, IPC (typical):** Pass  
Tested to J-STD-004B, IPC-TM-650, Method 2.6.3.7

## Availability

275 is available in a wide variety of alloys, wire diameters and flux percentages. For most applications, Sn63Pb37, Sn96.5Ag3.0Cu0.5 or K100LD is used. Please refer to [www.kester.com](http://www.kester.com) for wire diameters, flux percentages, alloys and roll sizes that are available.

Note: Core Size 50, 58 and 66 = 1.1%, 2.2% and 3.3% flux core.

## Process Considerations

Solder iron tip temperatures are most commonly between 315-343°C (600-650°F) for Sn63Pb37 and Sn62Pb36Ag02 alloys, and between 371-400°C (700-750°F) for lead-free alloys. Heat both the land area and component lead to be soldered with the iron prior to touching the land with the cored wire. Do not apply the wire directly to the soldering iron tip. If needed, Kester 959T or 958M no clean flux may be used as a compatible liquid flux to aid in reworking soldered joints. Kester 959T is available in Flux-Pen® for optimum board cleanliness.

## Cleaning

The 275 flux residues are non-corrosive, non-conductive and do not require removal in most applications. IPA will not clean the residues off the surface of the circuit board after the soldering process. A saponifier or cleaning agent specifically designed to clean a no-clean flux is required to clean the residues. Please contact Kester Technical Support for further information.

## Storage and Shelf Life

Storage must be in a dry, non-corrosive environment. The surface may lose its shine and appear a dull shade of gray. This is a surface phenomena and is not detrimental to product functionality. Flux cored solder wire has a limited shelf life determined by the alloy used in the wire. For alloys containing more than 70% lead, the shelf life is two years from the date of manufacture. Other alloys have a shelf life of three years from date of manufacture.

## Health and Safety

This product, during handling or use, may be hazardous to your health or the environment. Read the Safety Data Sheet (SDS) and warning label before using this product.